

EMB-LN9T

Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> Pass <input type="checkbox"/> Fail <input type="checkbox"/> Pass with Deviation Comment: _____			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date

2010/10/7

Approval

Jansin Lee

Test Engineer

Nisam Jone

Sample Configuration & Quantity Under Test

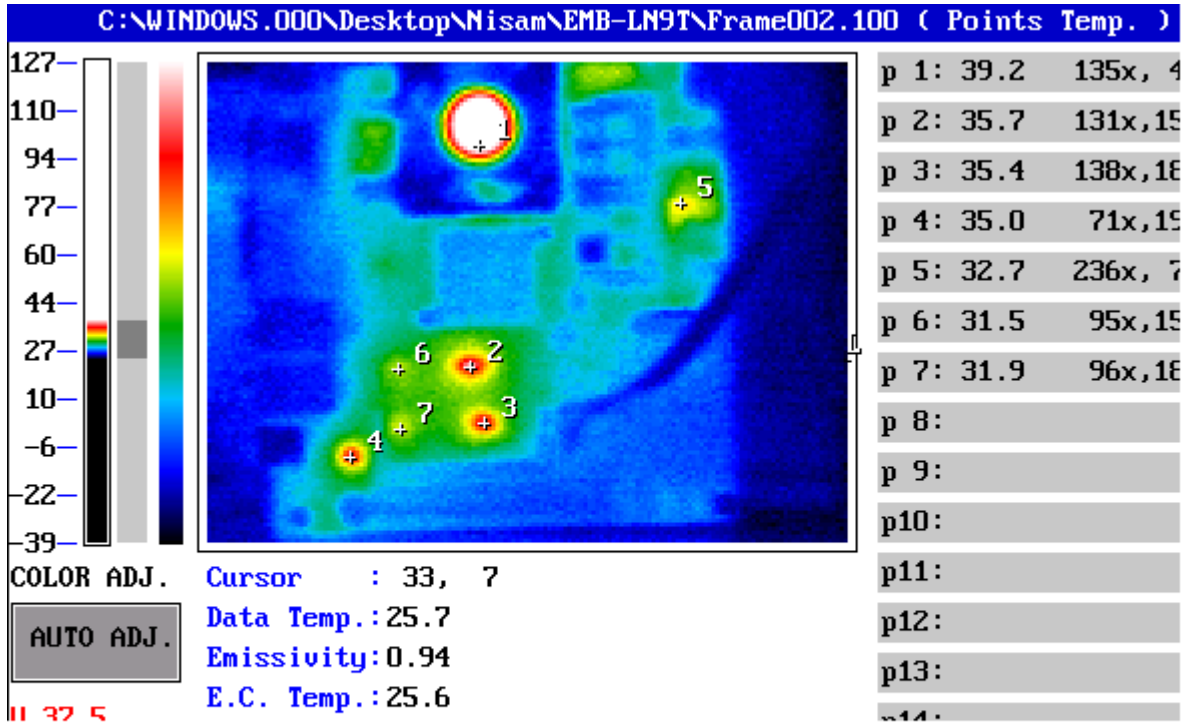
- CPU Board: EMB-LN9T A0.2
- Carrier Board:N/A
- CPU: Intel Atom D510 1.66GHz
- Memory: A-DATA DDR2 800 SODIMM 1GB (A-DATA AD29608A8A-25EG)
- HDD: WD(Western Digital) WD WD800AAJS 80GB
- BIOS : AMI 4.6.3.7 ELN9T 1.10 x64 09/09/2010
- Test Software: Windows XP sp3 / Run Prime95 v25.11
- ATX Power Supply: Seventeam ST-350BKV 350W
- Cooler:

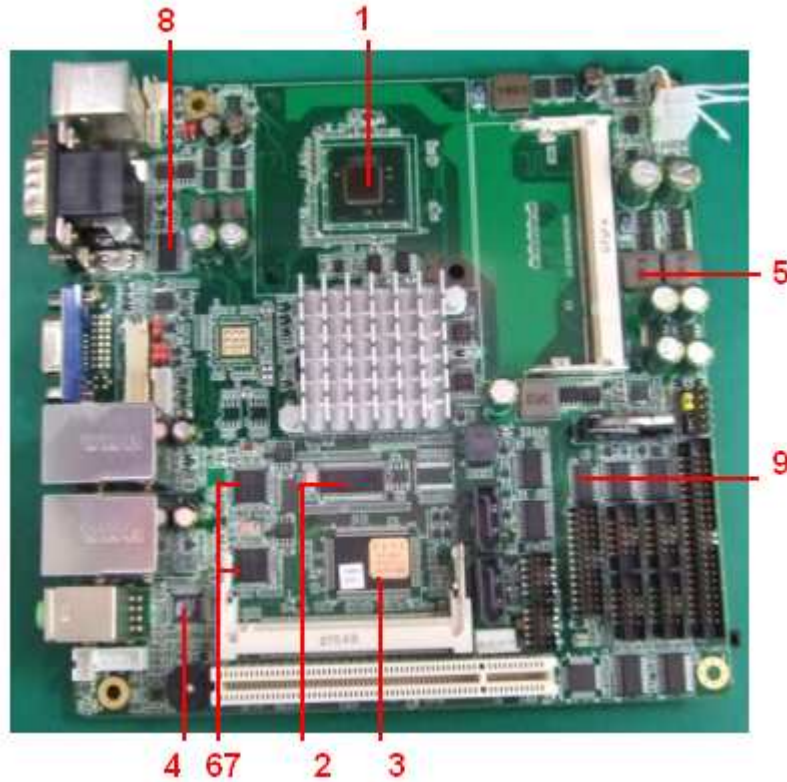


Thermal Image Analysis

1. Test Date: 10/07/2010
2. Test Product: EMB-LN9T
3. Test Site: AAEON QA Internal Lab.
4. Temperature Measurement:
 1. GRAPHTEC midi LOGGER TYPE - GL200
 2. IR Scanner: Infrared Camera
NIPPON AVIONICS CO., LTD.
Model: TVS-100
Date of Calibration: 09/17/09
Serial Number: 0179L2746
5. Test Condition:
Component Side-1 (Test by TVS-100 & TH-046): 25.6°C With cooler
Component Side-2 (Test by TVS-100): 25.6°C With cooler
6. Test Software:
Windows XP sp3 / Run Prime 95 v25.11
7. Take Picture Time:
After power on 2 hours

**Temperature Profile Test:
Component Side-1:**





Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.6°C	60°C	
1	U28	(TF)Intel CPU.Pineview D.DUAL CORE.D510.1.66GHz.Micro-FCBGA8.559Pins.AU80610004392A A SLBLA;EE-A100346;14S4166012;TWN	125	55.8	90.2	
2	U26	(TF)IC.SMD.TSSOP 64P.CLOCK GENERATOR.IDT.9LPRS501PGLF;EE-A081777;14S3050100;TW N	100	38.4	72.8	
3	U27	(TF)IC.SMD.PQFP 128P.LPC Super I/O.Winbond.W83627UHG	100	39.2	73.6	
4	U9	(TF)IC.SMD.LQFP 48P.7.1Channel HD Audio Codec.VIA.VT1708B	105	32.8	67.2	
5	L39	(TF)COIL.3.3uH.20%.SMD.11.5x10.5x4.0mm.DCR=10.8m ohm.Idc=10Amp.ZenithTek.ZPWM-1040MB-3R3M	155	35.4	69.8	
6,7	U16,U17	(TF)IC.SMD.QFN.64P.PCI-express.Gigabit Ethernet Chip.REALTEK.RTL8111C-VB-GR	100	33.0	67.4	
8	U6	(TF)IC.SMD.SSOP RS232 Driver ESD 15KV.AD.ADM213EARSZ	115	31.9	66.3	
9	U39	(TF)IC.SMD.QSOP 28P.IEEE 1284 Termination Network.CMD.PACSZ1284-04QR	115	31.9	66.3	

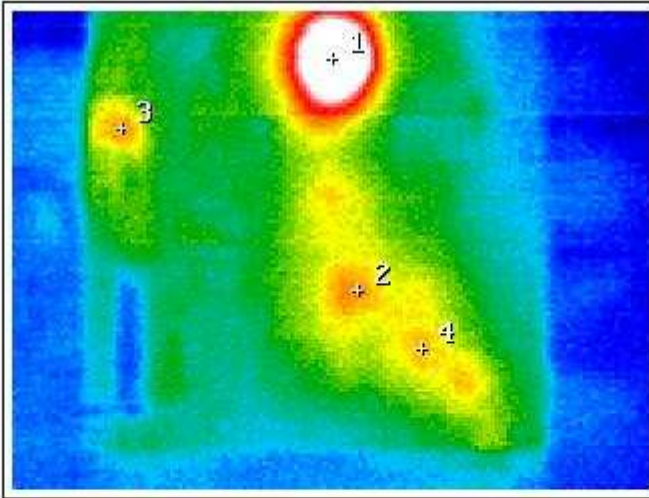
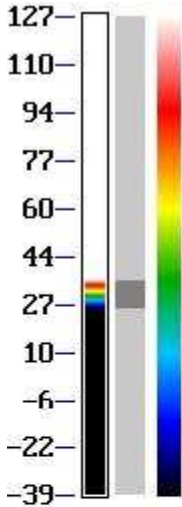
Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.

Component Side-2:



p 1:	42.5	160x, 23y
p 2:	32.8	173x, 139y
p 3:	32.5	54x, 58y
p 4:	32.1	205x, 168y
p 5:		
p 6:		
p 7:		
p 8:		
p 9:		
p10:		
p11:		
p12:		
p13:		
p14:		
p15:		

COLOR ADJ. Cursor : 51, 22
 Data Temp.: 30.5
 Emissivity: 0.94
 E.C. Temp.: 30.6
 Ambi Temp.: 26.8

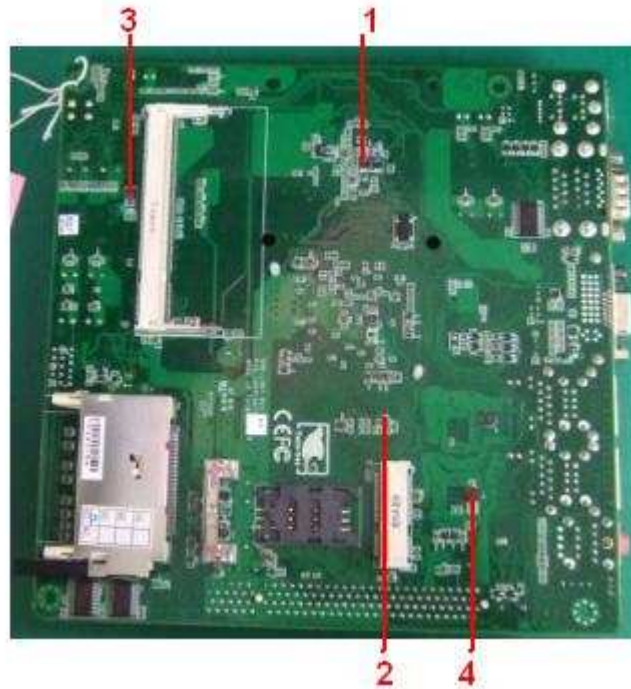
AUTO ADJ.

U 35.8
 D 25.8

HIGH(H) 41.77 X:160 Y: 22
 LOW(L) 26.53 X:312 Y: 54

Emissivity: 0.94

DATE : 2010/10/06
 TIME : 09:05:45



Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.6°C	60°C	
1	C452	(TF)POSCAP.330uF.2.5V.20%.C2(6*3.2*1.8).12mohm.3300mA.S MD.SANYO.2R5TPE330MCC2	135	42.5	76.9	
2	C427	(TF)MCC.10uF.10V.20%.X5R 0805.SMD	115	32.8	67.2	
3	C572	(TF)POSCAP.330uF.2.5V.20%.C2(6*3.2*1.8).12mohm.3300mA.S MD.SANYO.2R5TPE330MCC2	135	32.5	66.9	
4	L44	(TF)COIL.4.7uH.20%.SMD.3.85x3.85x1.8mm.DCR=146Ω IDC=1.1A.ZenithTek.ZSJ-3020S-4R7M	135	32.1	66.5	

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